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**Sensor apparatus, production method and detection
apparatus**

10 The invention relates to a sensor apparatus, in
particular a time-of-flight (TOF) and/or CCD sensor
apparatus for a 3-D camera sensor according to the
preamble of claim 1, a method for producing the sensor
apparatus according to the preamble of claim 13, and a
15 detection apparatus according to the preamble of claim
16.

20 While on the one hand there is a general trend toward
ever greater miniaturizations in the chip design, on
the other hand many chips and optoelectronic sensor
apparatuses can only be used to a very limited extent
and have to be implemented in some instances in a
complex manner with provision of some peripherals in
cameras or other sensor devices. Difficulties can
occur, in particular, because corresponding sensor
25 devices are too large and too complex, but often the
necessary robustness is also lacking with respect to
the application-related requirements.

30 It is an object of the invention to propose a sensor
apparatus and a method for producing it which enables
improved integration into application-based sensor
devices or detection apparatuses.

35 Proceeding from a sensor apparatus and a method for
producing it and a detection apparatus of the type
mentioned in the introduction, the object is achieved
by means of the characterizing features of claim 1, of
claim 13 and of claim 16.

Advantageous embodiments and developments of the invention are possible by means of the measures mentioned in the dependent claims.

5 Accordingly, a sensor apparatus according to the invention is distinguished by the fact that the circuit components including the analog/digital converter are integrated as an integrated circuit in a chip, wherein the chip is manufactured using 1-poly technology.

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The sensor apparatus according to the invention is, in particular, a time-of-flight (ToF) and/or CCD (charge coupled device) sensor apparatus for a 3-D camera sensor. A typical industrial application consists, for
15 example, in providing a monitoring apparatus for a door, a gate system or the like. The invention makes it possible to provide a so-called system-on-chip (SoC) for pixel-based detection of a 3-D area, which, in particular, is also suitable for industrial
20 applications. The sensor apparatus can serve as the principal element of a 3-D camera, that is to say as a 3-D camera sensor, wherein it is preferably embodied as a time-of-flight or CCD sensor apparatus.

25 The sensor apparatus according to the invention comprises at least one analog and digital circuit component and an analog/digital converter for converting analog signals of the analog circuit components into digital signals for the digital circuit
30 component, and vice versa. Both types of circuit components, namely analog and digital circuit components, in each case comprise so-called modules which enable electronic implementation of a function (e.g. data processing, data storage, driver functions,
35 phase adjustment, amplifications, etc.). In the case of the sensor apparatus according to the invention, one module of the analog circuit component is embodied as a sensor device for detecting electromagnetic radiation, in particular IR radiation. Consideration is preferably

given to applications in the field of optical or optoelectronic sensor technology (e.g. in the visible range (wavelength of approximately 400 nm - 800 nm), ultraviolet (UV) or IR range). The detection of
5 infrared radiation (IR radiation) can regularly be involved precisely in the case of monitoring systems. One important function of modules of the analog circuit component is, therefore, primarily the influencing, taking place in the actual sensor (ToF sensor, CCD), or
10 the transport of free charge carriers (free-charge handling).

Furthermore, at least one module of the digital circuit component is embodied as a signal processing device for
15 processing digital signals, a so-called digital domain for signal processing. Further functions which can be implemented by additional modules of the digital circuit component concern, for example, phase modulation, measurement and regulation of phase shifts,
20 if these functions are required for time-of-flight measurements, for example.

By virtue of the measure that the sensor apparatus is integrated in a single chip and a system-on-chip
25 solution is thus provided, the sensor apparatus according to the invention can be integrated particularly well into a wide variety of sensors, sensor apparatuses, cameras, monitoring apparatuses, etc. Besides the user-friendliness made possible by
30 this integration, the apparatus according to the invention additionally also affords cost advantages, since the individual, sometimes expensive, functional modules are already integrated in the one chip. In particular, the sensor apparatus according to the
35 invention or the system-on-chip according to the invention affords a particular space saving by virtue of which the possibilities of integration into a wide variety of application systems are additionally increased as well.

The sensor apparatus according to the invention in the form of a system-on-chip consequently enables the integration of modules for all the functions which are important for a sensor, as a result of which it can be implemented particularly advantageously into a wide variety of systems. As a result, by way of example, a detection apparatus which uses the sensor apparatus according to the invention can fulfill particular robustness with respect to a wide variety of application-related requirements (ambient light, detection of objects having different optical properties such as e.g. reflectivity).

The sensor apparatus according to the invention or the system-on-chip according to the invention is manufactured using 1-poly technology (single-polysilicon technology). Stacked double structures (2-poly) are thus avoided, and the construction thus becomes, in principle, flatter and additionally less complex. The entire chip, in particular also the CCD, can correspondingly be produced using 1-poly technology according to the invention. CCD chips are usually manufactured using 2-poly technology.

The integration of a non-volatile memory on the chip for storing configuration parameters, in particular an EEPROM (electrically erasable programmable read-only memory), is particularly preferred. This allows a crucial step toward a fully integrated system-on-chip which not only has a compact and space-saving design but also can itself in turn be integrated outstandingly into sensors and measuring apparatuses. Moreover, the robustness of such a fully integrated variant according to the invention can be increased significantly by comparison with conventional sensor apparatuses.

In one advantageous development of the invention, the EEPROM can be embodied as an FGFET (floating gate field effect transistor). Such an FGFET structure has a respective source and drain terminal, and additionally
5 a control terminal, the so-called control gate. A region designated as a floating gate is situated in the region of the control gate. Charges can be "stored" permanently in said region of the floating gate. Depending on the charge state of the floating gate
10 region, the source-drain path is at high impedance or low impedance. This difference can be used, for example, for coding the information to be stored.

A corresponding FGFET is then likewise embodied as a
15 1-poly structure. Consequently, the control gate is not embodied as a double structure in which the floating gate is situated below the control gate, said floating gate being separated from the rest of the bulk material by means of a gate oxide, rather the floating gate is
20 embodied as a layer that also extends over the region from source toward drain. In this case, the region of the control gate can be separated from the region of the source-drain path by means of a further field oxide region. The control gate can be arranged in the bulk
25 structure outside the source-drain path.

Since the floating gate does not form a stacked structure with the control gate in 1-poly design, the gate structure can, in particular, also comprise a
30 control gate in the form of a buried layer (buried control gate), which is arranged in the bulk material of the semiconductor itself (embodiments: e.g. ETOX, FLOTOX). In the case of this proposed design, moreover, it is also possible to save material for the oxide
35 layer that would otherwise be required for insulation in the case of a 2-poly structure.

In one preferred embodiment of the invention, subnominal gaps are formed in the analog circuit

component, while subnominal lines are manufactured in the digital circuit component. The term "subnominal" means below the critical dimension, i.e. below the smallest directly producible feature size. The
5 so-called bi-subnominal etching method serves as a production method for said lines and gaps, said etching method making it possible to produce particularly narrow structures which cannot be achieved using conventional etching methods and the associated masks.
10 By means of this method it is possible to produce structures which are below the minimum critical dimensions which can usually be achieved for a mask step. These narrow structures make it possible, in the case of semiconductor structure elements such as
15 EEPROMs or CCDs, to be able to influence charge carrier packets by means of fields, since the distances can be made correspondingly small, without structure overlaps or similar measures being necessary. Consequently, this production method is particularly suitable for
20 producing structures that are as small as possible, such as are often desired in the case of CCDs, for example, in order to achieve a smallest possible distance between the gate structures.

25 The digital circuit components can correspondingly comprise narrow lines, that is to say e.g. for short transistors, in order to enable transistors to be densely packed and thus in order to be able to obtain high performance in the signal processing.

30 Furthermore, the analog circuit components require narrow gaps for influencing and for transporting free charge carriers by means of fields and for detecting charge packets (so-called free-charge handling).

35 The analog/digital converter, by contrast, advantageously has wide lines owing to the tolerance with respect to high voltages.

With regard to the construction of the semiconductor structure of the sensor apparatus it is moreover conceivable, in principle, for analog and digital circuit components to be separated by so-called guard rings. Such guard rings are highly doped ring structures surrounding semiconductor structure regions to be delimited, such that it is thereby possible for the parasitic resistances to decrease and, on the other hand, it is in turn possible for stray charge carriers to be intercepted by the guard rings. Furthermore, it is possible to prevent semiconductor structures that are to be shielded from being driven on account of parasitic effects. Furthermore, individual modules can also be separated by guard rings.

A series of modules can be integrated on the chip according to the invention. In one exemplary embodiment, moreover, the digital circuit component can comprise at least one of the following modules (alongside the digital domain for signal processing, the A/D converter and the non-volatile memory):

- an apparatus for controlling a phase shift, in particular a DLL (delay-locked loop),
- a timer resonant circuit, in particular a PLL (phase-locked loop).

In addition, the analog circuit component can comprise at least one of the following modules (alongside the sensor and modules for so-called free-charge handling):

- a sensor for detecting radiation together with a structure for transporting induced free charge carriers,
- an amplifier,
- a voltage regulator,
- a voltage converter,
- a temperature sensor.

In one particularly preferred embodiment of the invention, on a sensor apparatus according to the

invention as a fully integrated system-on-chip, the following analog and digital modules can be integrated together: a TOF pixel matrix for optical detection, a voltage supply or voltage regulation, the non-volatile
5 memory for the corresponding configuration, an LED driver or an LED controller for the active illumination by the sensor apparatus, a digital SPI interface for communication, the A/D converter, the PLL and further data processing electronic components or electronic
10 components which can be used for volatile data storage.

The DLL can, for example, independently measure and regulate the phase shift between LED and LED driver. The timer is stabilized by a corresponding timer
15 resonant circuit (PLL).

The sensor for radiation detection is, for example, a pixel matrix which is embodied as a CCD and influences and transports radiation-induced free charge carriers
20 by means of fields. A temperature sensor in turn can be provided for performing a correction of the temperature drift of the entire sensor apparatus, wherein, by way of example, corresponding calibration data stored as configuration parameters in the EEPROM are used for
25 this purpose. By virtue of the fact that all these modules can be combined in a single system-on-chip, it is additionally possible to save expensive and space-consuming peripheral components such as FPGAs (field-programmable gate array) for processing logic,
30 A/D converters, components for power supply, etc.

The digital circuit components can be manufactured, in principle, in CMOS processes (complementary metal-oxide semiconductor).

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In the present case, a particular CMOS process is proposed for a sensor apparatus according to the invention, said CMOS process being distinguished by some advantages, precisely in the area of infrared

detection, by comparison with standard CMOS methods. Commercially available standard CIS sensors (abbreviation of "CMOS image sensor") comprise so-called pinned photodiodes, the photosensitive
5 detection region of which comprises only a thickness of a few micrometers, that is to say is smaller than the absorption length of light having a wavelength of 850 nanometers in silicon, namely an absorption length of approximately 13 micrometers. The high quantum
10 efficiency in the CMOS components now proposed is made possible firstly by illumination of the components from the back side (back-side illumination) and the extremely short detection times for the charge carriers formed in a detection.

15 The CCD sensor device can be constructed for example as follows: the semiconductor structure for photon detection comprises a substrate composed of a semiconductor material having a first doping, a contact
20 region applied to the front side of the substrate, a bias layer composed of a semiconductor material having a second doping, which is arranged on the back side of the substrate at a distance from the contact region, wherein the contact region is at least partly opposite
25 the bias layer, such that an overlap region is present in a lateral direction, a guard ring, which is arranged on the front side of the substrate and surrounds the contact region, wherein a reverse voltage can be applied between the contact region and the guard ring,
30 by virtue of the fact out that the overlap region has a lateral extent amounting to at least one quarter of the distance between the contact region and the bias layer. As a result of this solid relationship, it is possible not only for the potential in the bulk material to be
35 influenced by the potential applied to the contact region, but likewise the potential of the bias layer. A potential channel arises, a conduction channel between the contact region and the bias layer lying opposite. The bulk material can be obtained for the sensor

apparatuses using the float-zone method (float-zone silicon). This material is distinguished by very low defects and by particular homogeneity. The conductivity is from several hundred ohms x centimeter (Ω cm) to
5 several kilohms x centimeter ($k\Omega$ cm). The sensor apparatus according to the invention or the corresponding embodiment, by virtue of these measures, can make possible not just particularly good detection; these measures also permit the sensor apparatus to be
10 suitable for a wide variety of conditions, for instance under the influence of ambient light and in the case of a wide variety of optical properties of the objects to be detected, which can moreover move.

15 On account of their different functions, in one exemplary embodiment of the invention, the circuit components or the respective modules of the circuit components can be designed for different voltages. One function of modules of the analog circuit component
20 consists in the detection and influencing of charge packets (free-charge handling). The corresponding detection module is, for example, part of the TOF sensor. Further modules of the analog circuit component have as function inter alia voltage regulation and
25 voltage conversion, temperature detection, amplification for suppressing background noise, modules having a driver function for the light emitting diode, etc. Accordingly, it is advantageous for the modules of the analog circuit component to be designed for higher
30 voltages than those of the digital circuit component.

The analog and digital circuit components comprise semiconductor components in which oxide layers are used for electrical insulation. One example thereof is, for
35 instance, the gate oxide, which, in the case of a transistor, for example, separates or insulates the gate from the rest of the bulk material. In addition, other oxide layers can also be present, for example the field oxide or other intermediate oxide layers. In

order, accordingly, in the case of analog circuit components, to be able to avoid a voltage breakdown, advantageously in one development of the invention oxide layers of the analog circuit components are embodied as thicker than those of the digital circuit components. The thicknesses of the gate oxide of the EEPROM can be chosen to be smaller than the thicknesses of the gate oxide layers of the modules of the analog circuit component, but in turn greater than the thicknesses of the gate oxide layers in modules of the digital circuit component, e.g. the digital domain. Preferably, the gate oxide layers of the analog circuit components have a thickness of 9 nm to 15 nm, the gate oxide layer of the EEPROM has a thickness of 6 nm to 10 nm, and the gate oxide layer of the remaining digital circuit components has a thickness of 1.5 nm to 3 nm (where: nm: abbreviation of nanometer).

Furthermore, a method for producing a sensor apparatus according to the invention is correspondingly proposed. In particular, at least one part of the method for production can comprise a 200 nm CMOS manufacturing method. This involves a manufacturing method which firstly is established in semiconductor manufacture, but with regard to its accuracy makes requirements that still allow comparatively cost-effective production.

In one particularly preferred development of the invention, the gaps and lines of the semiconductor components are produced by means of a bi-subnominal etching method, which makes it possible to produce particularly narrow structures which cannot be achieved using conventional etching methods and the associated masks. This measure for production makes it possible, in particular, to be able to provide the sensor apparatus according to the invention as a fully integrated system-on-chip.

A detection apparatus according to the invention is distinguished by the fact that a sensor apparatus according to the invention is provided. The detection apparatus can serve, for example, as a monitoring
5 device which monitors the movement of a movement element, for instance of a gate or of a door. In this case, the intention is to avoid collisions with objects, for instance if persons encroach on a door gap and there is the risk of contusions or other articles
10 are trapped, in which case the drive of the door could also incur damage in the process.

The chip according to the invention can be soldered, for example, onto a printed circuit board. The printed
15 circuit board can be equipped with the voltage supply, for instance. If active illumination is required, the printed circuit board can, if appropriate, also carry a light source, such as e.g. light emitting diodes. A use of the sensor apparatus in a wide variety of sensor
20 devices is conceivable, in principle.

Exemplary embodiment:

An exemplary embodiment of the invention is illustrated
25 in the drawings and is explained more thoroughly below with indication of further details and advantages.

Specifically, in the figures:

30 Figure 1 shows a schematic illustration of a sensor apparatus (SoC) according to the invention;

Figure 2 shows a schematic illustration of the combination of the sensor apparatus with a
35 PCB according to the invention;

Figure 3 shows a commercially available 2-poly flash memory cell (EEPROM);

Figure 4 shows a schematic illustration (conceptual) of the transition from the 2-poly flash cell to the single-poly flash cell;

5 Figure 5 shows a schematic illustration of a 1-poly EEPROM;

10 Figures 6 to 17 show the sequence of a bi-subnominal etching method for semiconductor components on a substrate with feature sizes which are less than the critical dimensions, on the basis of schematic sectional diagrams.

15 Figures 18 to 29 show a variant of the etching method in accordance with figures 6 to 17.

Figure 1 shows a schematic illustration of a plan view of a sensor apparatus 1 according to the invention, which is embodied as a fully integrated system-on-chip. 20 The entire chip 1, as is illustrated in figure 1, has a size of 2.55 mm x 2.55 mm (where: mm: abbreviation of millimeter). Specifically, only the regions in which essential modules are arranged are illustrated; other electronics, conductor tracks or the like, which may be 25 illustrated in specific detail only with difficulty anyway in the size of the drawing, have been omitted in figure 1. The schematically illustrated component mounting plan shows, inter alia, the following modules and circuit components, namely the digital domain 2 for 30 signal processing, the pixel matrix 3 for detection, the voltage converter (charge pump) 4, the driver for the light emitting diode (LED) 5, the EEPROM 6 for storing configuration parameters, a module 7 comprising both a resonant circuit (PLL, phase-locked loop) and an 35 apparatus for measuring and regulating the phase shift between LED and LED driver (DLL, delay-locked loop).

Furthermore, a module is illustrated which has elements of analog and digital circuit components, namely the

A/D converter 8. Furthermore, contact areas 9 are illustrated. The system-on-chip 1 which is illustrated in figure 1 and which is manufactured using 1-poly technology is the particularly preferred embodiment of the invention. For monitoring purposes, the pixel matrix can comprise 8 x 8 pixels. Each pixel can operate independently of the others. Furthermore, each pixel in turn has two output channels which can be read and analyzed in order to determine the relative phase offset with respect to the phase of the emitted light. In the case of a monitoring sensor, it is basically sufficient to measure an individual distance, and so it suffices to form an average value over the pixels present and the read information thereof. The individual pixels can also be weighted differently.

For the illustrated embodiment of the chip 1, an individual voltage source suffices, which makes available a voltage of 8.5 V, since voltages required further are provided by means of integrated voltage converters. Since the sensor operates with active illumination, that is to say itself has a light source used for detection purposes, 1 to 3 LEDs are typically required as luminous means in the present case. The distance can be read out for example by means of PWM (pulse width modulation) or by means of an SPI register. Commands and setting of the registers can be effected by means of an SPI protocol.

The use of a CCD structure makes it possible, in particular, that the charge carrier packets can be influenced or detected in a short time. This is particularly important in connection with the use of TOF sensors, since the latter typically have to make detections in the range of a few nanoseconds. Essentially, the response to a short emitted light pulse of the LED is in this case recorded and measured. The sensor chip 1 additionally also makes it possible to perform distance measurements with regard to

articles having a different reflectivity. In this case, the distance can typically be from a few centimeters to several meters.

5 Figure 2 shows a schematic illustration of a sensor circuit 10 comprising a sensor apparatus as chip 11, which is applied on a printed circuit board 12 (PCB). For contact-connection, the chip 11 is soldered directly on the printed circuit board 12. For
10 contact-connection, so-called pads 13 are available on the printed circuit board 12. Said pads 13 or contact points produce the connection to further conductor tracks. The chip 11 is fitted on the pads 13 by means of solder balls 14. In the sensor region, the chip 11
15 is illuminated from the back side of the sensor. In this case, the incident photons 15 firstly impinge on a layer of filter material and microlenses 16. Situated thereunder in turn is the bulk material 17, which substantially consists of float-zone silicon. The
20 electronic circuits 18, which serve, inter alia, for detection, are situated on the unilluminated side of the sensor (the actual "front side" of the semiconductor component), facing the printed circuit board 12. That region of the bulk material 17 into
25 which the incident photons 15 pass is present as a full depletion zone. The photons 15 in turn generate charge carriers 19 in the bulk material 17, which can in turn be detected by the circuits 18 of the sensor.

30 The quantum efficiency of a photo detector is generally dependent on the following four factors:

- absorption properties of the bulk material (that is to say of silicon);
- the thickness of the non-sensitive layer in which
35 short recombination times of the charge carriers generated predominate (these recombination times are the limiting factor particularly for the UV range with short wavelengths);

- the thickness of the depletion zone, which means a cut-off in the long-wave range;
- the reflection properties of the surface.

5 Particularly in applications in the area of monitoring,
detection in the infrared range is often used. An
improvement in the UV range can be effected, for
example, by optimizing the aftertreatment on the back
side for ultra-thin, insensitive layers. In the UV
10 range, the absorption length in silicon is only a few
nanometers. However, in principle such an optimization
step has nothing to do with the CMOS process used. The
same applies to the surface properties on the detection
side, the back side of the semiconductor structure,
15 i.e. in particular to the reflectivity of the detection
window. The sensor illustrated in figure 2 has the
advantage, in particular, that, in principle, a large
area is available as a result of the illumination from
the back side. Float-zone silicon is used as bulk
20 material or as basic constituent. In the analog circuit
component, it is possible to employ voltages of the
order of magnitude of up to 12 V.

The sensor apparatus proposed enables a quantum
25 efficiency in a wavelength range of 520 nm to 900 nm of
more than 80%. In this case, the temporal accuracy is
even in the sub-nanosecond range. The sensor apparatus
can be operated with a speed of up to 100 frames per
second.

30 In one current embodiment, the entire sensor together
with the printed circuit board has a size of
17 mm x 28 mm, wherein the voltage supply, the
controller and two LEDs for active illumination are
35 already included in this case. The sensor is therefore
also suitable, in particular, for applications in the
area of monitoring, such that small, inconspicuous
monitoring sensors can be used.

Furthermore, the sensor apparatus has a comparatively low energy consumption. A particularly critical factor with regard to the energy consumption is the active illumination for distance measurement by means of a TOF sensor. If the illumination is chosen to be much too weak, this sometimes detrimentally affects the accuracy of the distance measurement. In the case of the present embodiment, an energy of only 30 fJ (femtojoules) per pixel suffices to generate a signal of approximately 100,000 electrons and thus to achieve a quantum efficiency of 80% at a wavelength of 850 nm of the incident light. Overall, the LEDs typically need to be switched on for only 50% of the required integration time.

TOF sensors are distinguished precisely by enabling the background produced by ambient light (for example sunlight) to be reduced. This firstly makes possible a particularly precise measurement, but also in turn makes it possible to lower the energy consumption, since the active illumination can be chosen to be weaker, in principle.

Figures 3 to 5 show a non-volatile memory in the form of an EEPROM 20. The EEPROM 20 is firstly manufactured using 2-poly technology in figure 3. The semiconductor structure has the terminals source S, drain D and, as control terminal, a control gate CG. The double structure composed of polysilicon comprises, in the region of the gate, the contact-connection of the control gate CG and a so-called floating gate FG stacked thereunder. Said floating gate FG serves for storing charges and thus for storing information. In the present case, the gate structure is situated on a bulk material 21 (here: p-type substrate). The floating gate FG is separated from the bulk material 21 by means of a gate oxide 22. In the edge region, the memory cell is insulated by a so-called field oxide 23. Furthermore, a tunnel oxide is provided. The charge

that is intended to be stored in the floating gate FG can be influenced by means of the tunnel effect. The terminals in the region of source S and drain D are in each case embodied as a highly doped (n+) layer N+ (n: 5 negative doping, "+" means high doping).

Figure 4 shows how the transition from the 2-poly structure to the 1-poly structure is effected conceptually. The double structure is as it were 10 "undone" in the region of the floating gate FG and "folded to the side". Otherwise, the imaginary structure from figure 4 generally corresponds to the structure from figure 3.

15 Figure 5 finally shows the 1-poly structure of the EEPROM 25. This flash memory cell no longer has a double layer structure. Outside the source-drain path S-D is present, by means of a field oxide 23 of the control gate as buried highly doped (n+) layer (buried 20 control gate). The control gate CG is situated below a gate oxide, the floating gate FG finally in turn being arranged thereabove. By means of the driving of the control gate CG, the floating gate FG is finally influenced, which, for its part, ensures that the 25 source-drain path S-D changes its resistance. The information to be stored can be correspondingly coded.

Bi-subnominal etching:

30 This involves a method for producing semiconductor components on a substrate comprising photolithographic patterning steps, in which method, on the substrate, a first layer to be patterned is applied and a second layer serving as a mask layer for the first layer to be 35 patterned is applied. In addition, a third layer serving as a mask for the second layer is applied, and at least two photolithographic patterning processes are carried out successively for the second layer, wherein, during one of the patterning processes, after the

production of a structure made from a photosensitive layer for the provision of a mask layer for a patterning process at the third layer, positive ramp angles are produced at the patterning edges of the third layer, as a result of which the structures remaining free, given a thickness h of the third layer, decrease in size by a value $D = 2 \cdot h / \tan \alpha$, and wherein, during the other of the patterning processes, after the production of a structure made from a photosensitive layer for the provision of a mask layer for a patterning process at the third layer, negative ramp angles β are produced at the patterning edges of the third layer, wherein the remaining structures, given a thickness h of the third layer, decrease in size by a value $W = 2 \cdot h / \tan \beta$, and wherein the second layer is patterned on the basis of the respectively patterned third layer.

The starting point is e.g. a wafer 100 composed of silicon having doped regions 101, etched structures 102, which are used e.g. as active regions of a transistor, in which the gaps between the etched structures are filled with insulation material, in processes such as e.g. STI (shallow trench isolation) or LOCOS (Local oxidation of silicon). A dielectric 103, serving as a dielectric for transistor structures, can be applied to the wafer 100. Finally, this insulation layer is followed by a layer composed of polysilicon, for example, which is used later for producing the gate of the transistors, for example with a thickness of 200 nm. The polysilicon layer bears the reference symbol 200 (see figure 6).

Afterward, an insulation layer, in particular a silicon oxide layer 300, is applied to the layer 200. This layer should have chemical properties which are different than those of the underlying layer 200 and has e.g. a thickness of 50 nm. Thus, this layer, after

its patterning, can be used as a mask for the patterning of the underlying layer.

5 A layer stack 400 is applied thereon, which layer stack can consist of different layers, e.g. an antireflection coating 401 and a photoresist layer 402 (see figure 7).

10 The photoresist layer is patterned in order to obtain a first mask for the underlying layer 401. In this case, only the structures with which gap widths smaller than the critical dimension are intended to be created are realized in the photoresist layer. It goes without saying that this mask step can also be used to produce structures which are larger than the minimum structure.

15 Furthermore, structures having a size of the minimum lines with regard to the critical dimension thereof can arise in this mask step. In principle, the criterion of the minimum feature size is complied with during the photolithographic process. The feature sizes smaller

20 than the minimum feature size arise as a result of a subsequent patterning step on the basis of a photolithographic process in the region of the minimum possible feature sizes.

25 A patterned photoresist layer 402 with openings 403 ultimately remains (see figure 8). The layer 401 is then patterned using this patterned photoresist layer. A preferred etching step advantageously takes place in such a way that a positive ramp angle arises in the

30 layer 401 at the edges of the structures. This produces in the layer 401 openings 420 which substantially have a constant offset of $D = 2 \cdot h / \tan \alpha$, where h is the thickness of the layer 401. The angle α is by definition the angle formed by the oblique boundary of

35 the layer 401 and the plane of the wafer. That means that an angle $\alpha > 90^\circ$ corresponds to a positive ramp angle, in the case of which openings 420 having a reduced size arise, whereas at an angle $\alpha < 90^\circ$ a negative ramp angle is present, in the case of which

openings increase in terms of dimension. In figure 9, openings 420 are reduced in size at any rate in the present step. The ramp angle is positive (see figure 9).

5

The underlying layer 300 (mask layer) is patterned using the patterned layer 401. This results in structures 320 (openings) in the layer 300 which correspond to the openings 420 in the layer 401 at the layer base thereof (see figure 10 and also figure 11).
10 In figure 11, the layer 402 and 401, respectively, is completely removed before the next process step.

In accordance with figure 12, a layer 411 and 412, respectively, is applied, wherein the layer 411 corresponds to the layer 401 and the layer 412 corresponds to the layer 402. The layer 412 is a photoresist layer which is patterned in accordance with the structures in which the intention is to achieve a
15 line width smaller than a line width which is still possible according to the critical dimension (see figure 13). Lines 430 can be seen in figure 13. These lines 430 are greater than or equal to the minimum line width using the photolithographic possibilities.

25

Using the patterned layer 412 with lines 430, the underlying layer 411 is patterned in such a way that negative ramp angles arise. As a result, the remaining lines 430 decrease in size by in each case the ramp
30 angle range, that is to say that the lines become smaller by the value $W = 2 \cdot h / \tan \beta$, where β is the angle between the substrate surface and the inwardly inclined edge (see figure 14 and figure 15).

35 Using the patterned lines 430 in the layer 411, the underlying layer 300 is patterned anew, wherein the width of the lines at the lower edge at the transition to the layer 300 is transferred to the underlying layer

300. Subnominal line structures that are smaller than the photolithographic line width arise.

Subsequently, the layers 412 and 411 are completely
5 removed and a renewed patterning operation is carried out using the patterned layer 300.

The layer 300 now contains subnominal gap widths and subnominal line widths in comparison with a critical
10 dimension at the predetermined locations. Of course, the layer 300 can contain larger structures and also structures which correspond to the critical dimension.

Using the patterned layer 300, the underlying layer 200
15 is patterned, with which the gates of the transistors are produced.

It is subsequently possible to remove the layer 300 to leave a patterned polysilicon layer 200 having
20 subnominal gaps 220 and subnominal lines 230 (cf. figure 17).

A conventional CMOS process can subsequently be carried out.
25

In order to use the minimum structures, an implantation for producing source/drain regions in the regions of subnominal gap widths should subsequently be avoided.

30 In the variant of the etching method in accordance with figures 18 to 29, the same layers are employed as in the method in accordance with figures 6 to 17, for which reason the same reference symbols are used for the layers and the structures. What are different from
35 the production method according to figures 6 to 17 in the production method according to figures 18 to 29 are the process sequence and the layer sequence. The production method illustrated by figure 18 to figure 21 corresponds to that in figures 6 to 9. In contrast to

the method in accordance with figures 6 to 17, however, the underlying mask layer 300 is not patterned by means of the patterned layer 401 after the production of the openings 420, rather the photoresist layer 402 is
5 completely removed (see figure 22) and a renewed photoresist layer (412) is applied. As in the method in accordance with figures 1 to 12, the layer 412 is patterned in accordance with the structures in which the intention is to achieve a line width smaller than a
10 line width which is still possible photolithographically according to the critical dimension. Lines 430 can be seen in figure 24. These lines 430 are greater than or equal to the minimum line width using the photolithographic possibilities.

15 Using the patterned layer 412 with lines 430, the underlying layer 400 is patterned in such a way that negative ramp angles arise. As a result, the remaining lines 430 decrease in size by in each case the ramp
20 angle range (see figure 25). The photoresist layer 412 is subsequently removed (see figure 26), a patterned layer 401 remaining which is used to pattern the underlying layer 300 (mask layer). In accordance with the width of the openings and lines, respectively, at
25 the base of the layer, these dimensions are transferred to the layer 300 in the patterning process, to be precise in a single patterning step, whereas two patterning steps are employed for the layer 300 in the method in accordance with figures 6 to 17.

30 The patterned layer 300 can be seen in figure 22. The further process sequence in accordance with figures 23 and 24 then corresponds once again to the process sequence in accordance with figures 16 and 17.

List of Reference Symbols:

1	System-on-chip
2	Digital domain
3	Pixel matrix
4	Voltage converter
5	LED driver
6	EEPROM
7	PLL/DLL module
8	A/D converter
9	Contact area
10	Sensor circuit
11	Chip
12	Printed circuit board
13	Pad
14	Solder ball
15	Light
16	Filter layer with microlenses
17	Bulk material
18	Electronic circuits
19	Charge carriers
20	2-poly EEPROM
21	p-type substrate
22	Gate oxide
23	Field oxide
24	Tunnel oxide
25	1-poly EEPROM
100	Wafer
101	Doped regions
102	Structures
103	Dielectric
200	polysilicon
220	Subnominal gaps
230	Subnominal line
300	Mask layer
320	Structures
400	Layer stack
401	BARC layer

402	Photoresist
403	Opening
411	BARC layer
412	Photoresist
420	Opening
430	Line
CG	Control gate
D	Drain terminal
FG	Floating gate
N+	(n+) layer
S	Source terminal

Claims:

1. A time-of-flight (TOF) and/or CCD sensor apparatus for a 3-D camera sensor, which comprises at least one analog and one digital circuit component and an analog/digital converter for converting analog signals of the analog circuit component into digital signals for the digital circuit component, and vice versa, wherein the analog circuit component and the digital circuit component in each case comprise at least one module for electronically implementing a function, and wherein one of the at least one module of the analog circuit component is a sensor device for detecting electromagnetic radiation and one of the at least one module of the digital circuit component is a signal processing device for processing digital signals, wherein the circuit components including the analog/digital converter are integrated as an integrated circuit in a chip and the chip is manufactured as a semiconductor structure using 1-poly technology.
2. Sensor apparatus according to Claim 1, wherein at least one of the modules of the digital circuit component is a non-volatile memory, for storing configuration parameters.
3. Sensor apparatus according to Claim 2, wherein the non-volatile memory is an EEPROM (electrically erasable programmable read-only memory).
4. Sensor apparatus according to any of the preceding claims, wherein the digital circuit component is manufactured using CMOS technology.

5. Sensor apparatus according to Claim 3, wherein the EEPROM is a FGFET (floating gate field effect transistor).

6. Sensor apparatus according to Claim 5, wherein the FGFET comprises a control gate structure with a buried layer (buried control gate).

7. Sensor apparatus according to any of the preceding claims, wherein subnominal gaps are formed in the analog circuit component and/or subnominal lines are formed in the digital circuit component.

8. Sensor apparatus according to any of the preceding claims, wherein the digital circuit component comprises at least one of the following modules:

- an apparatus for controlling a phase shift, in particular a DLL (delay-locked loop),
- a timer resonant circuit, in particular a PLL (phase-locked loop).

9. Sensor apparatus according to any of the preceding claims, wherein the analog circuit component comprises at least one of the following modules:

- a sensor for detecting radiation together with a structure for transporting induced free charge carriers,
- an amplifier,
- a voltage regulator,
- a voltage converter,
- a temperature sensor for detecting and correcting temperature-dictated drift.

10. Sensor apparatus according to any of the preceding claims, wherein the analog

circuit components are designed for higher voltages than the digital circuit components.

11. Sensor apparatus according to any of the preceding
5 claims, wherein the analog and digital circuit components
 comprise semiconductor components having oxide layers for
 electrical insulation, in particular having a gate oxide
 layer, wherein at least one of the oxide layers of the analog
 circuit components is thicker than that of the digital circuit
10 components.

12. Sensor apparatus according to any of the preceding
 claims, wherein the gate oxide layer of the analog circuit
 component has a thickness of 9 nanometers to 15 nanometers,
15 the gate oxide layer of the EEPROM has a thickness of 6
 nanometers to 10 nanometers, and the gate oxide layer of the
 remaining digital circuit component has a thickness of 1.5
 nanometers to 3 nanometers.

20 13. Method for producing a sensor apparatus according to
 any of the preceding claims, the method comprising,
 providing one analog and one digital circuit
 component and an analog/digital converter for converting
 analog signals of the analog circuit component into digital
25 signals for the digital circuit component, and vice versa,
 wherein the analog circuit component and the digital circuit
 component in each case comprise at least one module for
 electronically implementing a function, and wherein one of the
 at least one module of the analog circuit component is a sensor
30 device for detecting electromagnetic radiation and one of the
 at least one module of the digital circuit component is a
 signal processing device for processing digital signals,
 integrating the circuit components including the
 analog/digital converter as an integrated circuit in a chip,
35 and
 using 1-poly technology to manufacture the chip as a
 semiconductor structure.

14. Method according to Claim 13, wherein at least one part of the method comprises a 200 nm CMOS manufacturing method.

5 15. Method according to Claims 13 or 14, wherein subnominal gaps and/or subnominal lines of the sensor apparatus are produced by means of a bi-subnominal etching method.

10 16. Detection apparatus, in particular a monitoring apparatus for monitoring the movement of a movement element against undesired collisions with an object, wherein a sensor apparatus according to any of Claims 1 to 12 is provided for detecting the object.